RELIABILITY REPORT

FOR

MAX4478AUD+

PLASTIC ENCAPSULATED DEVICES

July 2, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX4478AUD+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX4475-MAX4478/MAX4488/MAX4489 wideband, low-noise, low-distortion operational amplifiers offer rail-to-rail outputs and single-supply operation down to 2.7V. They draw 2.2mA of quiescent supply current per amplifier while featuring ultra-low distortion (0.0002% THD+N), as well as low input voltage-noise density (4.5nV/) and low input current-noise density (0.5fA/). These features make the devices an ideal choice for applications that require low distortion and/or low noise. For power conservation, the MAX4475/MAX4488 offer a low-power shutdown mode that reduces supply current to 0.01µA and places the amplifiers' outputs into a high-impedance state. These amplifiers have outputs which swing rail-to-rail and their input common-mode voltage range includes ground. The MAX4475-MAX4478 are unity-gain stable with a gain-bandwidth product of 10MHz. The MAX4488/4489 are internally compensated for gains of +5V/V or greater with a gain-bandwidth product of 42MHz. The single MAX4475/MAX4476/MAX4488 are available in space-saving, 6-pin SOT23 and TDFN packages.

II. Manufacturing Information

A. Description/Function:	SOT23, Low-Noise, Low-Distortion, Wide-Band, Rail-to-Rail Op Amps
B. Process:	B12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon, California or Texas
E. Assembly Location:	Thailand
F. Date of Initial Production:	July 28, 2001

III. Packaging Information

A. Package Type:	14-pin TSSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3858
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	110°C/W
K. Single Layer Theta Jc:	30°C/W
L. Multi Layer Theta Ja:	100.4°C/W
M. Multi Layer Theta Jc:	30°C/W

IV. Die Information

A. Dimensions:	72 X 140 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 156 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 7.0 \times 10^{-9}$

$\lambda = 7.0$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the B12 Process results in a FIT Rate of 0.06 @ 25C and 1.06 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The OX50 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX4478AUD+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	156	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data